

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P <sub>PP</sub>	90	W	8/20μs, Per Figure 3
Peak Pulse Current	I <sub>PP</sub>	2	A	8/20μs, Per Figure 3
ESD Protection – Contact Discharge	V <sub>ESD_Contact</sub>	±20	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	V <sub>ESD_Air</sub>	±20	kV	IEC 61000-4-2 Standard

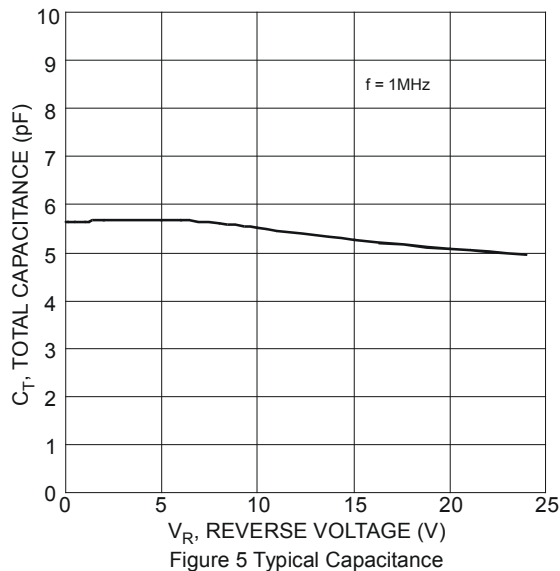
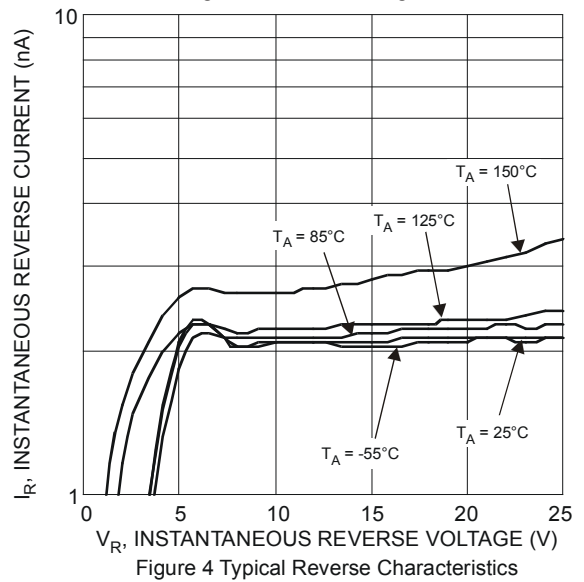
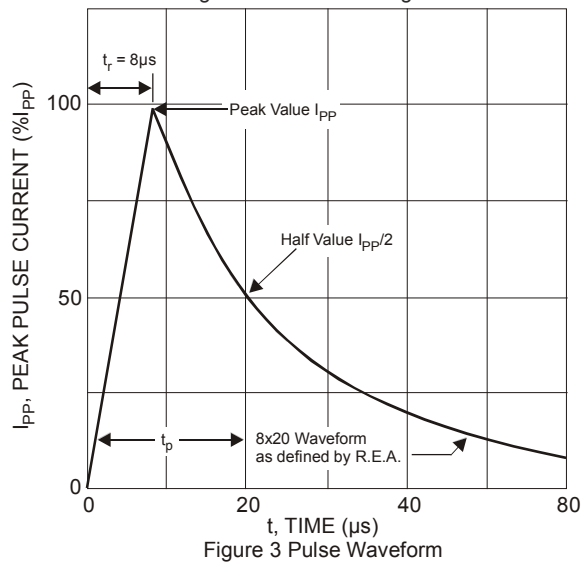
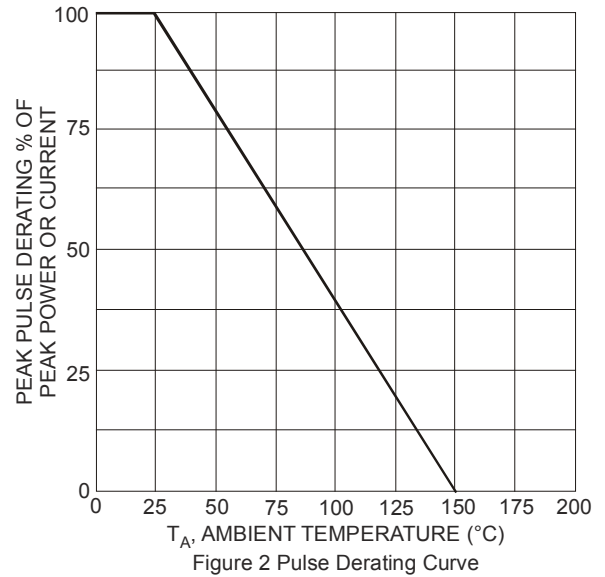
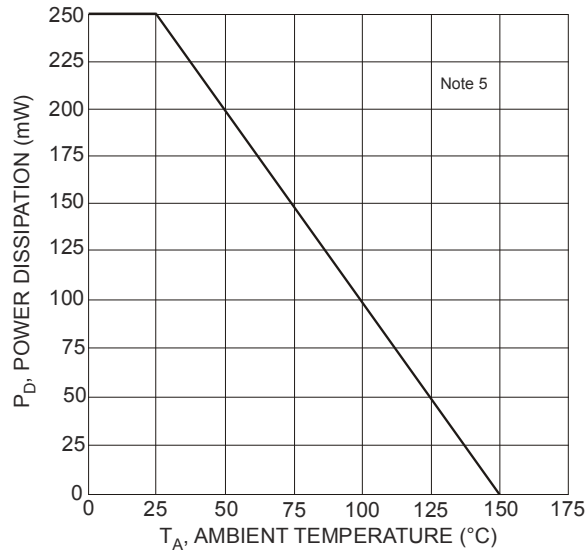
**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P <sub>D</sub>	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V <sub>RWM</sub>	—	—	24	V	—
Channel Leakage Current (Note 6)	I <sub>RM</sub>	—	—	100	nA	V <sub>RWM</sub> = 24V
Clamping Voltage, Positive Transients	V <sub>CL</sub>	—	—	42	V	I <sub>PP</sub> = 1A, t <sub>p</sub> = 8/20μS
		—	—	46	V	I <sub>PP</sub> = 2A, t <sub>p</sub> = 8/20μS
Breakdown Voltage	V <sub>BR</sub>	26	—	32	V	I <sub>R</sub> = 1mA
Channel Input Capacitance	C <sub>T</sub>	—	6	10	pF	V <sub>R</sub> = 0V, f = 1MHz

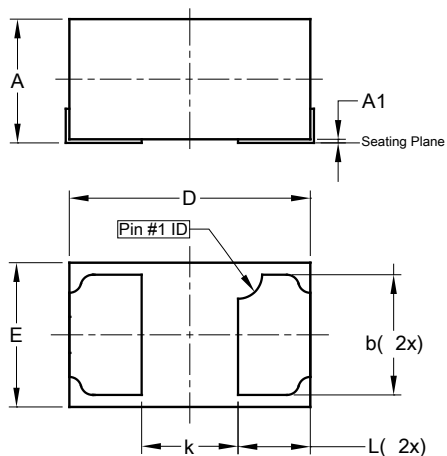
Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.  
6. Short duration pulse test used to minimize self-heating effect.



## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN1006-2 (SWP)

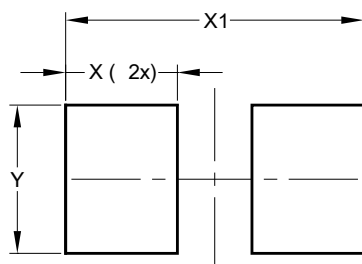


U-DFN1006-2/SWP			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.0	0.05	0.03
b	0.45	0.55	0.50
c	0.55 REF		
D	0.95	1.05	1.00
E	0.55	0.65	0.60
h	0.17 REF		
k	0.37 REF		
L	0.25	0.35	0.30
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN1006-2 (SWP)



Dimensions	Value (in mm)
X	0.45
X1	1.20
Y	0.60

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